FLAT-BASE TYPE INSULATED PACKAGE

PM100CL1A120



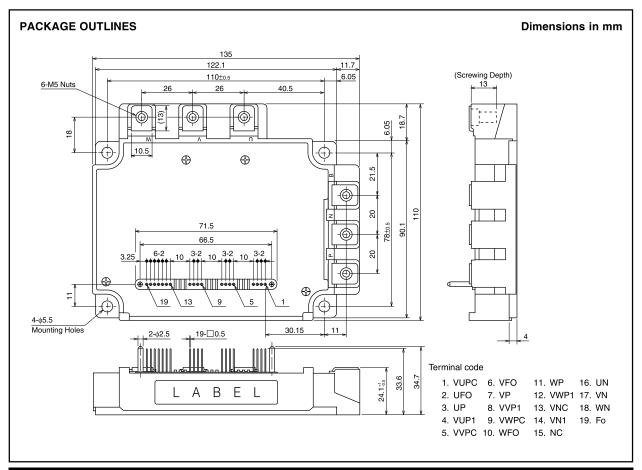
FEATURE

Inverter + Drive & Protection IC

- a) Adopting new 5th generation Full-Gate CSTBTTM chip
- b) The over-temperature protection which detects the chip surface temperature of $\mathsf{CSTBT^{TM}}$ is adopted.
- c) Error output signal is possible from all each protection upper and lower arm of IPM.
- d) Compatible L-series package.
 - 3\phi 100A, 1200V Current-sense and temperature sense IGBT type inverter
 - Monolithic gate drive & protection logic
 - Detection, protection & status indication circuits for, shortcircuit, over-temperature & under-voltage (P-Fo available from upper arm devices)
 - · UL Recognized

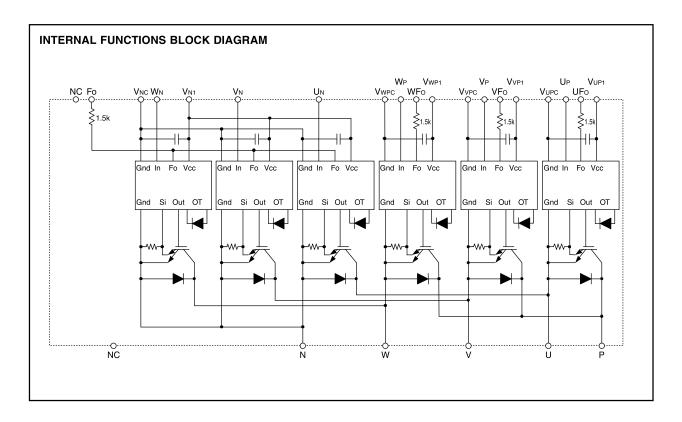
APPLICATION

General purpose inverter, servo drives and other motor controls





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$\label{eq:maximum ratings} \textbf{MAXIMUM RATINGS} \ (T_j = 25^{\circ}C, \ unless \ otherwise \ noted)$ $\label{eq:maximum ratio} \textbf{INVERTER PART}$

Symbol	Parameter	Condition		Ratings	Unit
VCES	Collector-Emitter Voltage	VD = 15V, VCIN = 15V		1200	V
±Ιc	Collector Current	Tc = 25°C	(Note-1)	100	Α
±ICP	Collector Current (Peak)	Tc = 25°C		200	Α
Pc	Collector Dissipation	Tc = 25°C	(Note-1)	657	W
Tj	Junction Temperature			− 20 ~ +150	°C

^{*:} Tc measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Condition	Ratings	Unit
VD	Supply Voltage	Applied between: Vup1-Vupc, Vvp1-Vvpc Vwp1-Vwpc, Vn1-Vnc	20	V
VCIN	Input Voltage	Applied between : UP-VUPC, VP-VVPC, WP-VWPC UN • VN • WN-VNC	20	٧
VFO	Fault Output Supply Voltage	Applied between : UFO-VUPC, VFO-VVPC, WFO-VWPC FO-VNC	20	V
IFO	Fault Output Current	Sink current at UFO, VFO, WFO, FO terminals	20	mA



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TOTAL SYSTEM

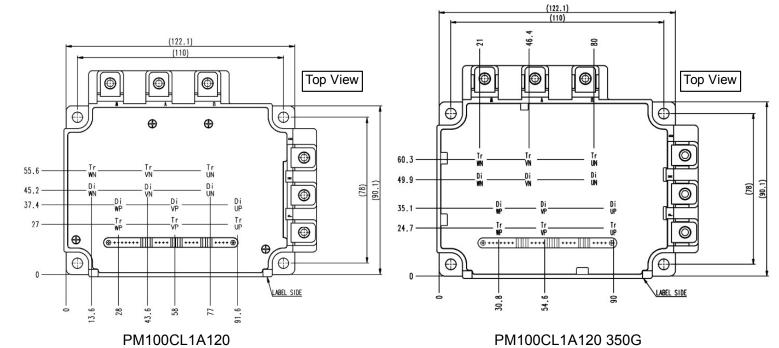
Symbol	Parameter	Conditions	Ratings	Unit
V _{CC(PROT)}	Supply Voltage Protected by SC	V_D =13.5V ~ 16.5V Inverter Part, T_i =+125°C Start	800	V
V _{CC(surge)}	Supply Voltage (Surge)	Applied between : P-N, Surge value	1000	V
T _{stg}	Storage Temperature		-40 ~ +125	°C
V _{iso}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V

 $[\]ensuremath{^*:}\ensuremath{\mathsf{T}_{\mathbb{C}}}$ measurement point is just under the chip.

THERMAL RESISTANCE

Symbol	Parameter	Conditions		Limits		
Symbol	i arameter			Тур.	Max.	Unit
$R_{th(j-c)Q}$	Thermal Resistance	Inverter, IGBT (per 1 element) (Note.1)	-	-	0.19	
$R_{th(j-c)F}$		Inverter, FWDi (per 1 element) (Note.1)	-	-	0.31	°C/W
R _{th(c-f)}	Contact Thermal Resistance	Case to fin, (per 1 module)			0.023	C/VV
Tth(c-f)	Contact Thermal Nesistance	Thermal grease applied (Note.1)	-	_	0.023	

Note.1: If you use this value, $R_{\text{th(f-a)}}$ should be measured just under the chips.



* "350G" is printed on the label

ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Conditions			Limits		Unit
Syllibol	Farameter	Conditions		Min.	Тур.	Max.	Offic
V	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V _D =15V, I _C =100A	T _j =25°C	-	1.65	2.15	V
V _{CE(sat)}		V_{CIN} =0V, Pulsed (Fig. 1) T_j =	-	1.85	2.35	\ \	
V _{EC}	FwDi Forward Voltage	-I _C =100A, V _D =15V, V _{CIN} = 15V	(Fig. 2)	-	2.3	3.3	V
t _{on}				0.3	0.8	2.0	
t _{rr}		$V_D=15V$, $V_{CIN}=0V \longleftrightarrow 15V$		-	0.3	0.8	
t _{c(on)}	Switching Time	V _{CC} =600V, I _C =100A T _i =125°C		-	0.4	1.0	μs
t _{off}		Inductive Load (Fig. 3,4)	(Fig. 3.4)	-	1.2	2.8	
t _{c(off)}			(i.ig. 5, i)	-	0.4	1.2] [
	Collector-Emitter Cut-off	V _{CE} =V _{CES} , V _D =15V , V _{CIN} =15V (Fig. 5)	T _j =25°C	-	-	1	mA
I _{CES}	Current V _{CE} =V _{CES}	VCE-VCES, VD-13V, VCIN-13V (FIG. 5)	T _j =125°C	-	-	10	IIIA



FLAT-BASE TYPE INSULATED PACKAGE

CONTROL PART

Cumbal	Danie marten	Condition			Limits		1.1
Symbol	Parameter	Condition	Condition		Тур.	Max.	Unit
lo	Circuit Current	urrent VD = 15V, VCIN = 15V	Vn1-Vnc	_	6	12	m 1
טו	Circuit Current		V*P1-V*PC	_	2	4	mA
Vth(ON)	Input ON Threshold Voltage	Applied between : UP-Vupc, VP-Vvpc,	WP-VWPC	1.2	1.5	1.8	· V
Vth(OFF)	Input OFF Threshold Voltage	Un • Vn • Wn-Vnc		1.7	2.0	2.3	V
SC	Short Circuit Trip Level	–20 ≤ Tj ≤ 125°C, VD = 15V	(Fig. 3,6)	200	_	_	Α
toff(SC)	Short Circuit Current Delay Time	VD = 15V	(Fig. 3,6)	_	0.2	_	μs
ОТ	O To	ver Temperature Protection Detect Temperature of IGBT chip	Trip level	135	_	_	့င
OT(hys)	Over remperature Protection		Hysteresis	_	20	_	U
UV	Supply Circuit Under-Voltage	–20 ≤ T _i ≤ 125°C	Trip level	11.5	12.0	12.5	V
UVr	Protection	-20 ≤ 1j ≤ 125 C	Reset level	_	12.5	_	V
IFO(H)	Fault Output Current	VD = 15V, VCIN = 15V	(Note-2)	_	_	0.01	mA
IFO(L)	Tault Output Current	VD = 13V, VCIN = 13V	(14016-2)	_	10	15	шд
tFO	Minimum Fault Output Pulse Width	VD = 15V	(Note-2)	1.0	1.8	_	ms

(Note-2) Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

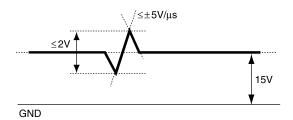
MECHANICAL RATINGS AND CHARACTERISTICS

	Barranta	Condition		Limits			Unit
Symbol	Parameter			Min.	Тур.	Max.	Unit
_	Mounting torque	Mounting part scre	ew : M5	2.5	3.0	3.5	N•m
	Mounting torque	Main terminal part scre	ew : M5	2.5	3.0	3.5	N•m
_	Weight	_		_	800	_	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Condition	Recommended value	Unit
Vcc	Supply Voltage	Applied across P-N terminals	≤ 800	V
VD	Control Supply Voltage	Applied between: VuP1-VuPC, VvP1-VvPC VwP1-VwPC, Vn1-VnC (Note-3)	15.0 ± 1.5	V
VCIN(ON)	Input ON Voltage	Applied between: UP-VUPC, VP-VVPC, WP-VWPC	≤ 0.8	\ _\ \
VCIN(OFF)	Input OFF Voltage	Un • Vn • Wn-Vnc	≥ 9.0]
fPWM	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
tdead	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig. 7)	≥ 2.5	μs

(Note-3) With ripple satisfying the following conditions: dv/dt swing $\leq \pm 5V/\mu s$, Variation $\leq 2V$ peak to peak



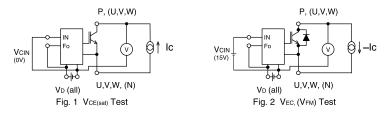


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PRECAUTIONS FOR TESTING

- Before applying any control supply voltage (VD), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
 After this, the specified ON and OFF level setting for each input signal should be done.
- 2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above VCEs rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)



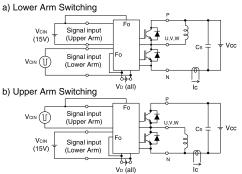


Fig. 3 Switching Time and SC Test Circuit

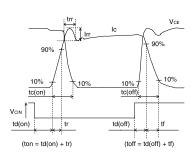


Fig. 4 Switching Time Test Waveform

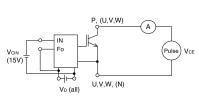


Fig. 5 Ices Test

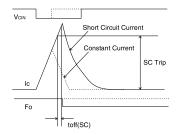
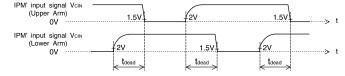


Fig. 6 SC Test Waveform



1.5V: Input on threshold voltage Vth(on) typical value, 2V: Input off threshold voltage Vth(off) typical value

Fig. 7 Dead time measurement point example



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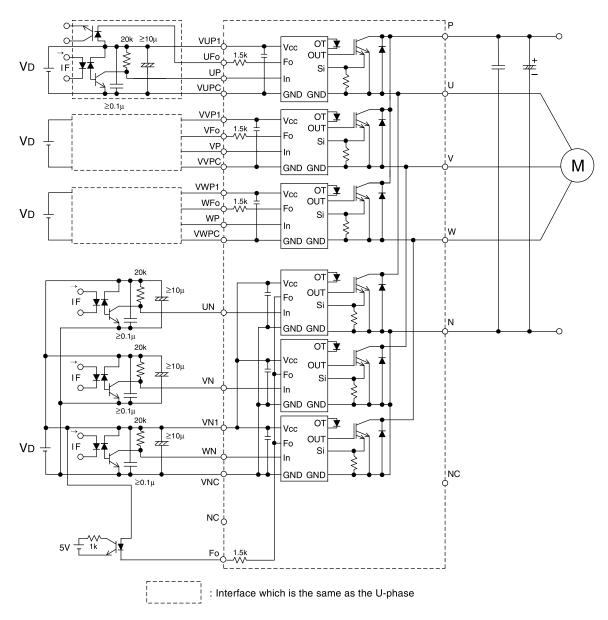


Fig. 8 Application Example Circuit

NOTES FOR STABLE AND SAFE OPERATION;

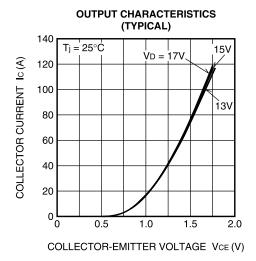
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- ●Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: tPLH, tPHL ≤ 0.8μs, Use High CMR type.
- ●Slow switching opto-coupler: CTR > 100%
- Use 4 isolated control power supplies (VD). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- •Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.
- Use line noise filter capacitor (ex. 4.7nF) between each input AC line and ground to reject common-mode noise from AC line and improve noise immunity of the system.



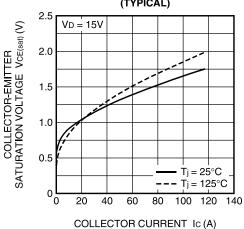
November 2012

FLAT-BASE TYPE INSULATED PACKAGE

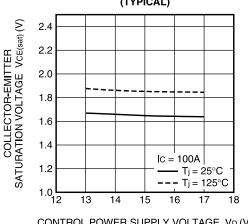
PERFORMANCE CURVES



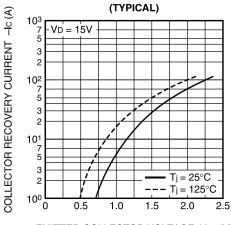
COLLECTOR-EMITTER SATURATION VOLTAGE (VS. Ic) CHARACTERISTICS (TYPICAL)



COLLECTOR-EMITTER SATURATION VOLTAGE (VS. VD) CHARACTERISTICS (TYPICAL)



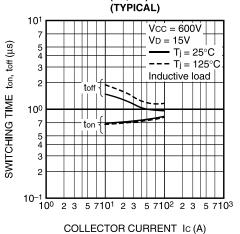
DIODE FORWARD CHARACTERISTICS



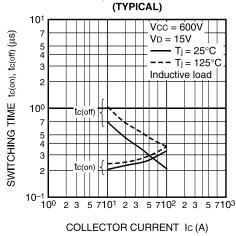
CONTROL POWER SUPPLY VOLTAGE VD (V)

EMITTER-COLLECTOR VOLTAGE VEC (V)

SWITCHING TIME (ton, toff) CHARACTERISTICS



SWITCHING TIME (tc(on), tc(off)) CHARACTERISTICS

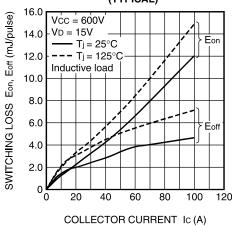




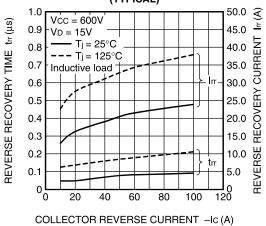


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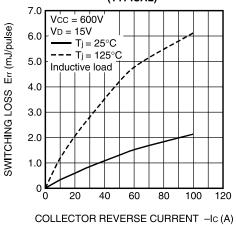
SWITCHING LOSS CHARACTERISTICS (TYPICAL)



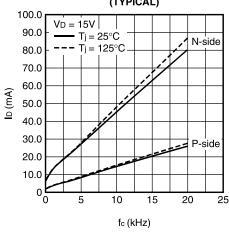
DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



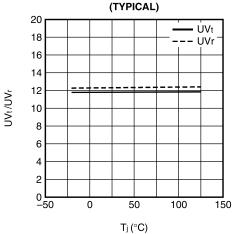
SWITCHING RECOVERY LOSS CHARACTERISTICS (TYPICAL)



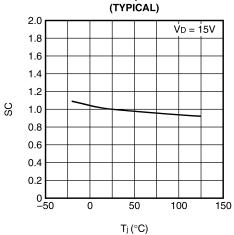
ID VS. fc CHARACTERISTICS (TYPICAL)



UV TRIP LEVEL VS. Tj CHARACTERISTICS



SC TRIP LEVEL VS. Tj CHARACTERISTICS

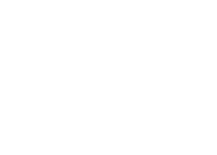




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TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (TYPICAL) 100 7 5 3 2 10-1 7 5 10-2 7 5 10-2 7 5 10-3 3 2 Single Pulse 10-3 10-3 2 Fer unit base = Rth(j-c)Q = 0.19°C/W 10-3 10-323 5710-3

t(sec)





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